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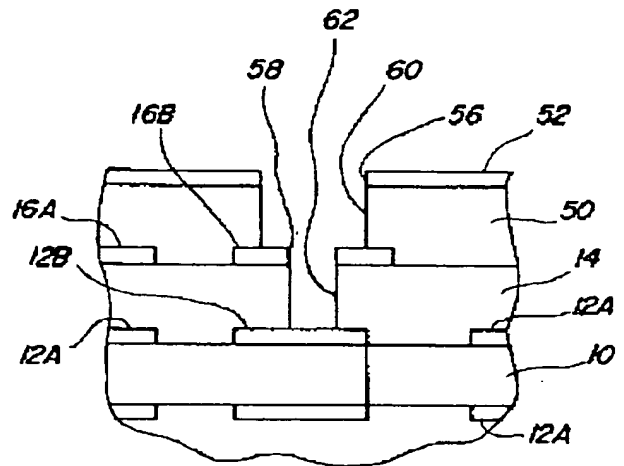
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TITLE : MANUFACTURE OF MULTILAYERED
PRINTED WIRING BOARD



ABSTRACT : PROBLEM TO BE SOLVED: To reduce the working manhour of a via-hole, by almost coaxially forming small holes having smaller diameters in order from the surface side of a laminate, in lands except lands of the lowermost layer, and forming via- holes with laser which penetrate the small holes of a plurality of lands from the surface of the laminate and reach the lands of the lowermost layer.

SOLUTION: In a copper foil 52 of a laminate wherein a board 50 is laminated, a small hole 56 is formed by eliminating a position for forming a via-hole by photo etching or the like. In the position where the via-hole is formed, lands 12B, 16B of circuit patterns 12A, 16A formed on boards 10, 14 are superimposed in the thickness direction of the laminate. Excepting the land 12B of the circuit pattern 12A which turns to the bottom of the via-hole, in the land 16B above the land 12B and in the outermost copper foil 52, a small hole 58 and the small 56 are so formed that the diameter becomes larger toward the surface side. Thereby via-holes 60, 62 are formed at the same time when the small hole 56 is irradiated perpendicularly to the laminate surface with laser.

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